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FCPF099N65S3

N-Channel SuperFET[®] III MOSFET 650 V, 30 A, 99 m Ω

Features

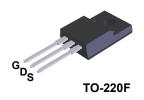
- 700 V @ T_J = 150 °C
- Typ. $R_{DS(on)}$ = 85 m Ω
- Ultra Low Gate Charge (Typ. Q_q = 57 nC)
- Low Effective Output Capacitance (Typ. C_{oss(eff.)} = 517 pF)
- · 100% Avalanche Tested
- · RoHS Compliant

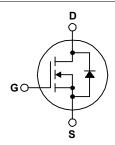
Applications

- · Telecom / Sever Power Supplies
- · Industrial Power Supplies
- UPS / Solar

Description

SuperFET[®] III MOSFET is ON Semiconductor's brand-new high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low on-resistance and lower gate charge performance. This advanced technology is tailored to minimize conduction loss, provide superior switching performance, and withstand extreme dv/dt rate. Consequently, SuperFET III MOSFET is very suitable for various power system for miniaturization and higher efficiency.





Absolute Maximum Ratings T_C = 25°C unless otherwise noted.

Symbol		Parameter		FCPF099N65S3	Unit	
V_{DSS}	Drain to Source Voltage			650	V	
V	Cata ta Carraga Valtaga	- DC		±30	V	
V_{GSS}	Gate to Source Voltage	- AC	(f > 1 Hz)	±30	V	
	Drain Current	- Continuous (T _C = 25°C)		30*	Α	
ID	Drain Current	- Continuous (T _C = 100°C)		19*	7 ^	
I _{DM}	Drain Current	- Pulsed	(Note 1)	75*	Α	
E _{AS}	Single Pulsed Avalanche Energ	ıy	(Note 2)	145	mJ	
I _{AS}	Avalanche Current		(Note 1)	4.4	Α	
E _{AR}	Repetitive Avalanche Energy		(Note 1)	0.43	mJ	
dv/dt	MOSFET dv/dt			100	V/ns	
αν/αι	Peak Diode Recovery dv/dt		(Note 3)	20	V/IIS	
Б	Dower Discipation	(T _C = 25°C)		43	W	
P_{D}	Power Dissipation - Derate Above 25°C		0.34	W/°C		
T _J , T _{STG}	Operating and Storage Temperature Range			-55 to +150	οС	
T _L	Maximum Lead Temperature fo	r Soldering, 1/8" from Case for 5 S	econds	300	οС	

^{*}Drain current limited by maximum junction temperature.

Thermal Characteristics

Symbol	Parameter	FCPF099N65S3	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	2.94	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max.	62.5	C/VV

Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FCPF099N65S3	FCPF099N65S3	TO-220F	Tube	N/A	N/A	50 units

Electrical Characteristics $T_C = 25^{\circ}C$ unless otherwise noted.

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Off Chara	cteristics					
D) /	Drain to Course Prockdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 1 \text{ mA}, T_J = 25^{\circ}\text{C}$	650	-	-	V
BV _{DSS}	Drain to Source Breakdown Voltage	$V_{GS} = 0 \text{ V, } I_D = 1 \text{ mA, } T_J = 150^{\circ}\text{C}$	700	-	-	V
ΔBV _{DSS} / ΔΤ _J	Breakdown Voltage Temperature Coefficient	I _D = 1 mA, Referenced to 25°C	-	0.68	-	V/°C
	Zoro Coto Voltago Drain Current	V _{DS} = 650 V, V _{GS} = 0 V	-	-	1	^
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 520 V, T _C = 125°C	-	1.4	-	μА
I _{GSS}	Gate to Body Leakage Current	V _{GS} = ±30 V, V _{DS} = 0 V	-	-	±100	nA

On Characteristics

V _{GS(th)}	Gate Threshold Voltage	$V_{GS} = V_{DS}$, $I_D = 3 \text{ mA}$	2.5	-	4.5	V
R _{DS(on)}	Static Drain to Source On Resistance	V _{GS} = 10 V, I _D = 15 A	ı	85	99	mΩ
9 _{FS}	Forward Transconductance	V _{DS} = 20 V, I _D = 15 A	-	19	-	S

Dynamic Characteristics

C _{iss}	Input Capacitance	V _{DS} = 400 V, V _{GS} = 0 V,	-	2310	-	pF
C _{oss}	Output Capacitance	f = 1 MHz	-	50	-	pF
C _{oss(eff.)}	Effective Output Capacitance	V _{DS} = 0 V to 400 V, V _{GS} = 0 V	-	517	-	pF
C _{oss(er.)}	Energy Related Output Capacitance	V _{DS} = 0 V to 400 V, V _{GS} = 0 V	-	77	-	pF
Q _{g(tot)}	Total Gate Charge at 10V	V _{DS} = 400 V, I _D = 15 A,	-	57	-	nC
Q_{gs}	Gate to Source Gate Charge	V _{GS} = 10 V	-	14	-	nC
Q_{gd}	Gate to Drain "Miller" Charge	(Note 4)	-	23	-	nC
ESR	Equivalent Series Resistance	f = 1 MHz	-	0.4	-	Ω

Switching Characteristics

t _{d(on)}	Turn-On Delay Time			-	22	-	ns
t _r	Turn-On Rise Time	$V_{DD} = 400 \text{ V}, I_{D} = 15 \text{ A},$		-	20	-	ns
t _{d(off)}	Turn-Off Delay Time	V_{GS} = 10 V, R_g = 4.7 Ω		-	58	-	ns
t _f	Turn-Off Fall Time		(Note 4)	-	5	-	ns

Source-Drain Diode Characteristics

Is	Maximum Continuous Source to Drain Diode Forward Current			-	30	Α
I _{SM}	Maximum Pulsed Source to Drain Diode Forward Current			-	75	Α
V_{SD}	Drain to Source Diode Forward Voltage V _{GS} = 0 V, I _{SD} = 15 A		-	-	1.2	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0 V, I _{SD} = 15 A,	-	374	-	ns
Q _{rr}	Reverse Recovery Charge	$dI_F/dt = 100 A/\mu s$	-	7.2	-	μС

Notes:

- 1. Repetitive rating: pulse-width limited by maximum junction temperature.
- 2. I_{AS} = 4.4 A, R_{G} = 25 Ω , starting T_{J} = 25°C.
- 3. I $_{SD} \leq$ 15 A, di/dt \leq 200 A/µs, V $_{DD} \leq$ 400 V, starting T $_{J}$ = 25°C.
- 4. Essentially independent of operating temperature typical characteristics.

Typical Performance Characteristics

Figure 1. On-Region Characteristics

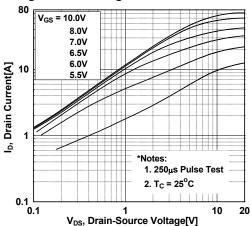


Figure 3. On-Resistance Variation vs.

Drain Current and Gate Voltage

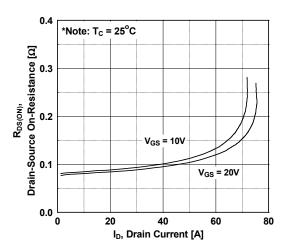


Figure 5. Capacitance Characteristics

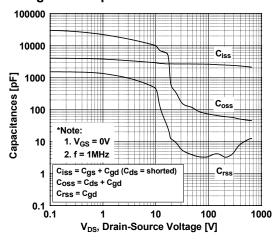


Figure 2. Transfer Characteristics

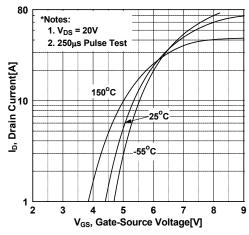


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

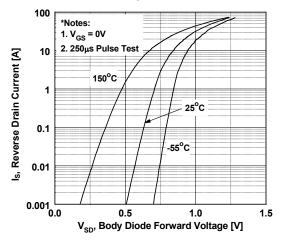
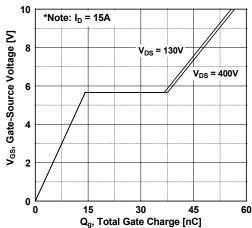


Figure 6. Gate Charge Characteristics



Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

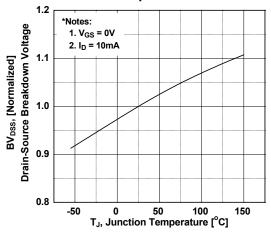


Figure 9. Maximum Safe Operating Area

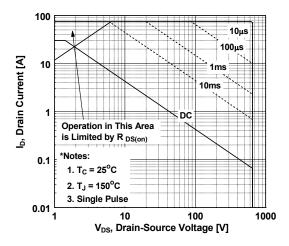


Figure 11. Eoss vs. Drain to Source Voltage

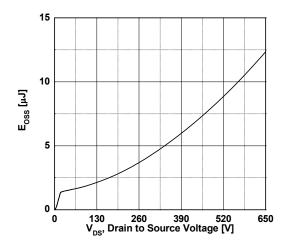


Figure 8. On-Resistance Variation vs. Temperature

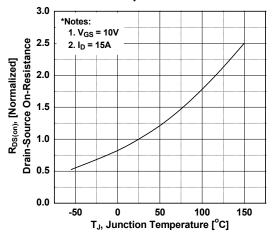
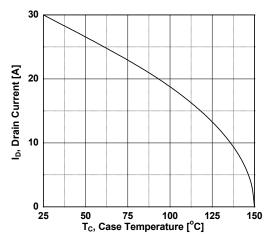
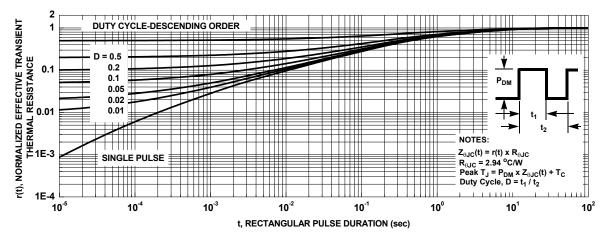


Figure 10. Maximum Drain Current vs. Case Temperature



Typical Performance Characteristics (Continued)

Figure 12. Transient Thermal Response Curve



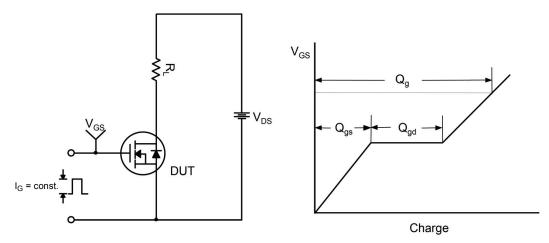


Figure 13. Gate Charge Test Circuit & Waveform

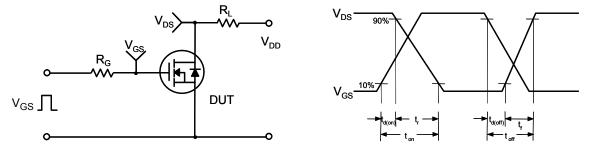


Figure 14. Resistive Switching Test Circuit & Waveforms

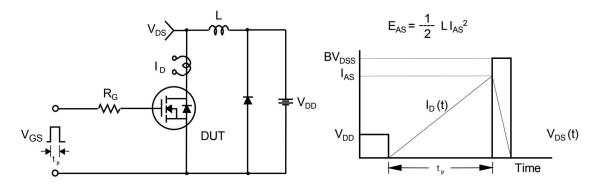
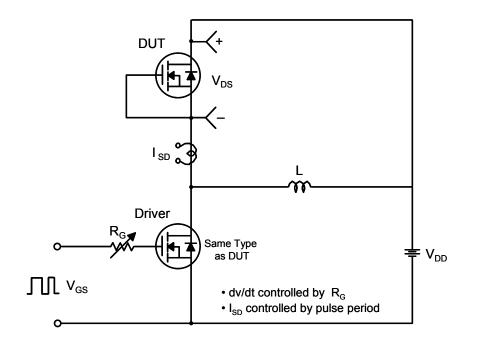


Figure 15. Unclamped Inductive Switching Test Circuit & Waveforms



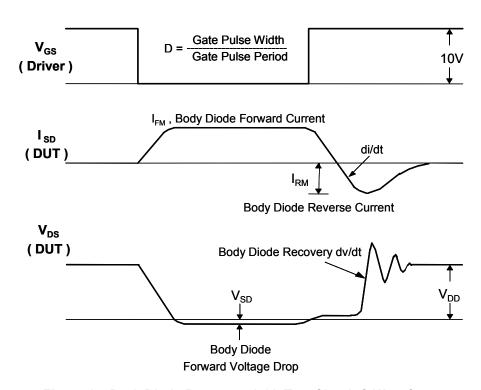
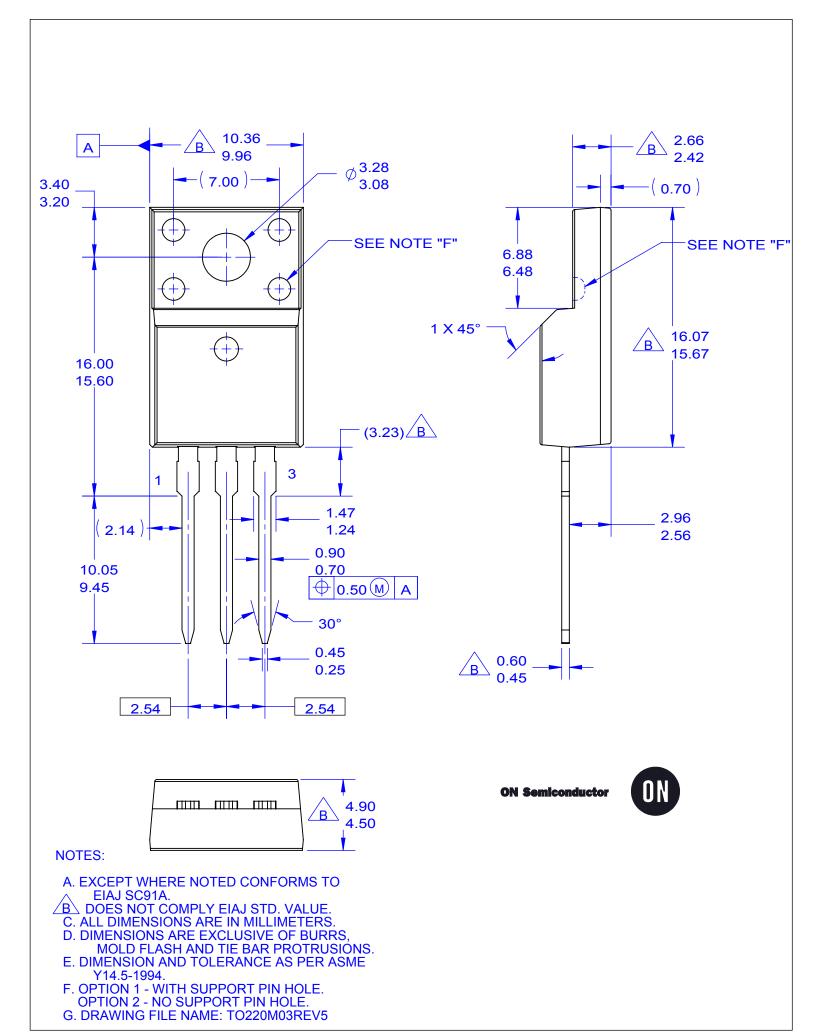


Figure 16. Peak Diode Recovery dv/dt Test Circuit & Waveforms



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